

L Number	Hits	Search Text	DB	Time stamp
1	1	("20020062923").PN.	US-PGPUB	2003/11/03 01:00
2	601	((Chip or die) and (solder adj mask)) with substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 01:04
3	245	((Chip or die) and (solder adj mask)) with substrate) and (@ad<20000118)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 01:04
4	23	((((Chip or die) and (solder adj mask)) with substrate) and (@ad<20000118)) and ((solder adj mask) with (adhesive or bismaelimide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/03 01:05